

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	71	hous\$4 and packag\$3 and die and grid near array and side near1 wall\$ and circuit	USPAT; EPO; JPO; DERWEN T	2003/02/23 22:17
2	BRS	L2	53	("3337838" "3366915" "3444506" "3676748" "3676993" "4167647" "4331831" "4423468" "4437718" "4487463" "4572604" "4616406" "4655526" "4660069" "4675472" "4698663" "4705917" "4734042" "4766479" "4897055" "4931908" "4943846" "4975066" "4989318" "4997376" "5008734" "5022144" "5037311" "5049974" "5071363" "5081563" "5091772" "5123164" "5137456" "5138438" "5182853" "5220491" "5281151" "5283717" "5285104" "5309024" "5326936" "5327325" "5334279" "5342999" "5347429" "5351393" "5371404" "5376825" "5390412" "5403784" "5428505" "5438224") .PN.	USPAT	2003/02/23 22:11
3	BRS	L3	0	pack\$3 and sie near wall\$ and lead\$ and semiconductor	USPAT; EPO; JPO; DERWEN T	2003/02/23 22:30
4	BRS	L4	139328	semiconductor and pack\$3 and side near wal(die or chip) and plate	USPAT; EPO; JPO; DERWEN T	2003/02/23 22:31
				semiconductor and pack\$3	USPAT; EPO;	

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	1329	4 and insulat\$3 same side near wall\$	USPAT; EPO; JPO; DERWEN T	2003/02/23 22:37